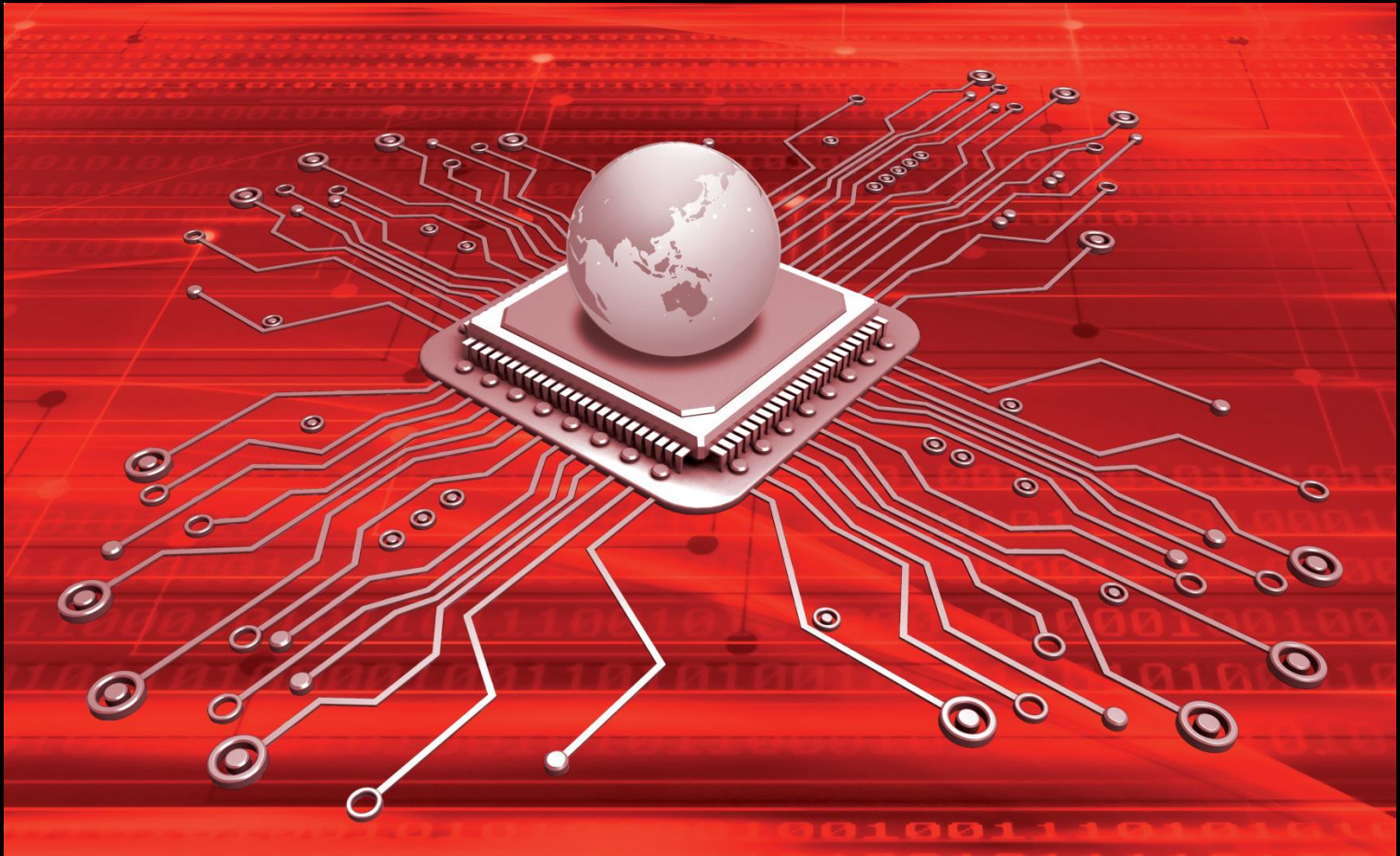


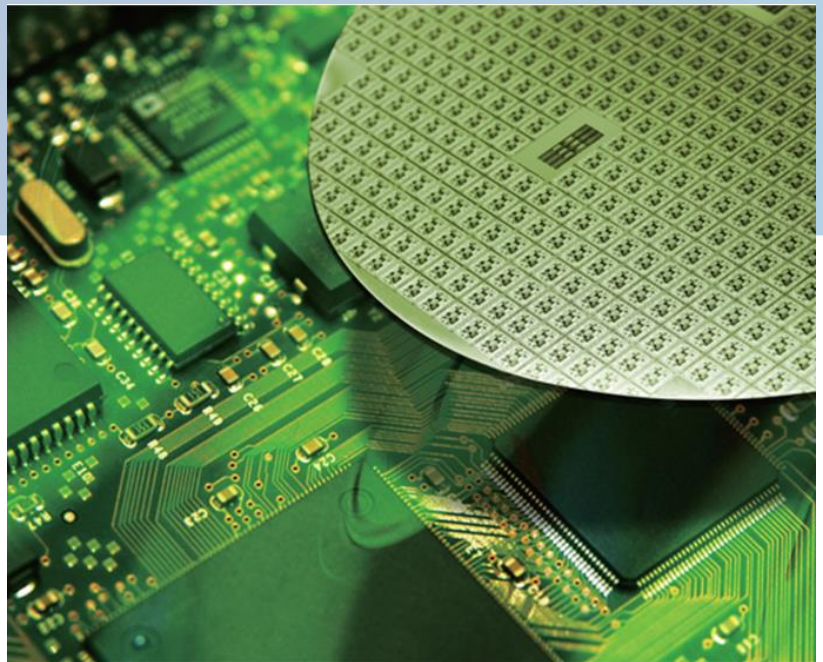
SemiHow SUPER JUNCTION MOSFET Selection Guide



신의와 정의로 고객에게 믿음을 주는 기업
Warm Faith AND Good Feeling

The most powerful Partner for you!

- Green Power Semiconductor -

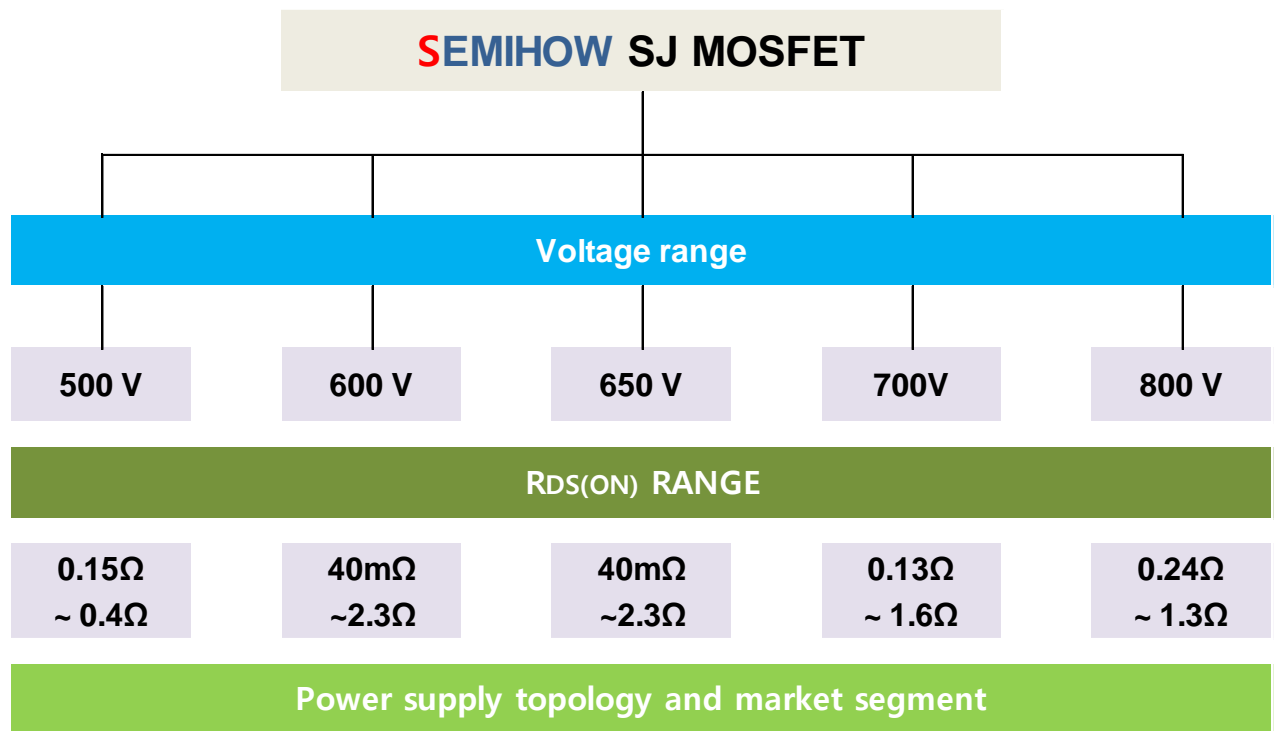


SemiHow SUPER JUNCTION MOSFET

Super Junction MOSFET of SemiHow ("SJ MOSFET" hereinafter) uses SemiHow's own cutting-edge technology for LED lighting and Consumer application.

SJ MOSFET shows better efficiency, thermal management and cost-efficiency in comparison with Planar MOSFET.

We're trying to do our best to offer support for various inquiries from customers such as short lead time, technical support and so on.



Adapter/charger/Quasi-resonant flyback



PC power PFC/TTF, PFC/LLC



LCD TV / LLC half-bridge

LCD TV adapter / Quasi-resonant flyback



LED drivers, PFC/LLC
Non-isolated bulk

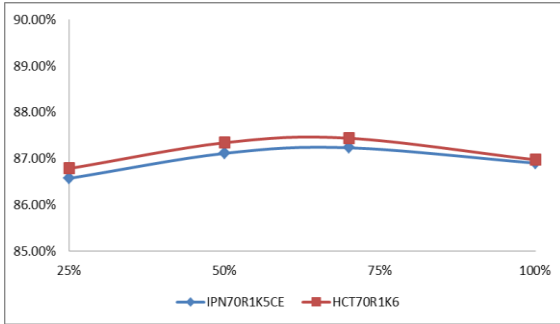
LED drivers / Quasi-resonant flyback

Benefit	
Various line-up	500 ~ 800V / SOT-223 ~ TO-247
Capacity of production	Running designated FAB and PKG line for stable supply of product
Lead time	Managing delivery efficiently (e.g. Intermediate amount : within 8 weeks)
Quality	Managing defective rate below 0.1 ppm
Circuit design	Full-time support by SemiHow's FAE

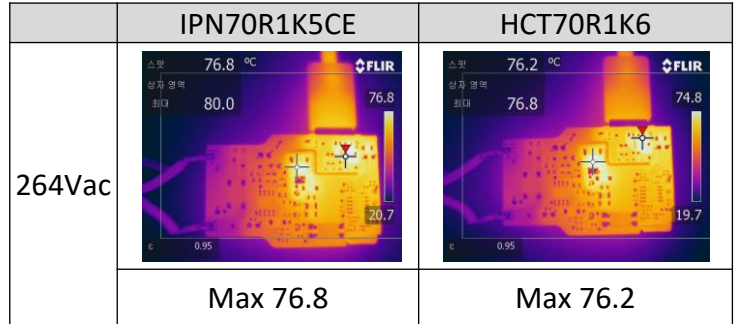
Smartphone & Tablet chargers

Charger for Smartphone, Tablet PC requires maximum output power from smaller size. For this reason, strict requirement regarding system cost are needed according to increasing power density, managing heating, emitting EMI and etc.. Most of OEM companies requires the temperature of case below 50°C and MOSFET below 90°C.

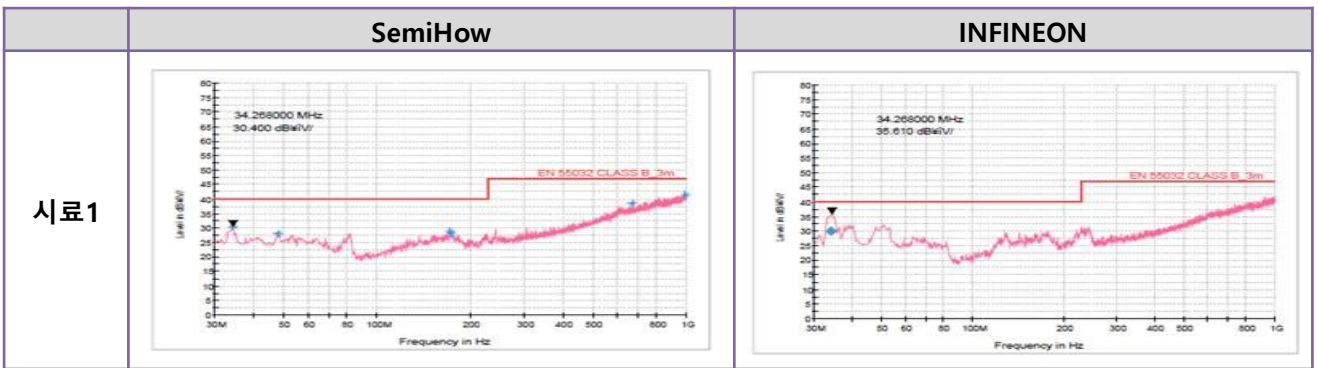
1. Feature test of HCT70R1K5E (15W Quick charger for GALAXY S9)



[Efficiency]



[Temperature]



[EMI - RE]

2. ESD Evaluation

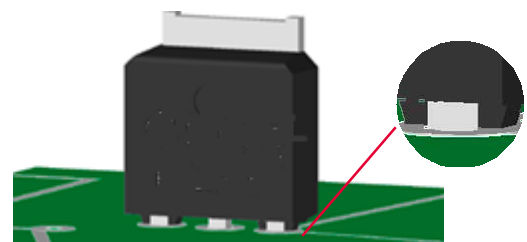
Device	HCT70R1K6 (New of DB)	HCT70R1K5E (Trench)	infineon 70R1K4CE	UTC 5NM70
ESD (HBM)	<3000V	< 800V	< 800V	< 800V
Class	CLASS 2	CLASS 1B	CLASS 1B	CLASS 1B

3. SemiHow PKG for Charger NOTE



SOT-223

Optimized PKG for Minimum space



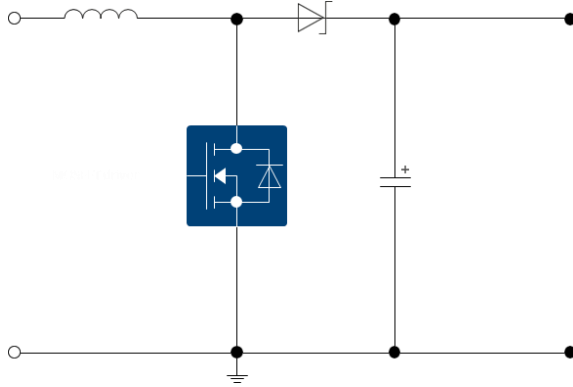
TO-251B (Short Lead with Isolation)

- Can enhance productivity of customers through including Mold Stopper for protecting from leakage current based on wafer level and contaminants
- Mold Bumps of 0.3mm are ideal for maintaining a well-defined distance between the PCB and the package body and a larger effective distance on insulating

APPLICATION

• Single switch topologies – Boost / PFC

High power adaptors, PC power, TV power supplies of front-end



Design equations for MOSFET selection

$$V_{DS} = V_{out}$$

$$I_D = I_{out} * 1 / (1-D)$$

$$V_{DS_FET} = 1.5 * V_{DS} \text{ (with derating for all variables on board)}$$

$$R_{DS(on)} \text{ max. } 25^\circ\text{C for acceptable power dissipation in MOSFET package} \\ = (1.5 * P_{device}) / (I_{pk}^2 * D). I_{pk} \text{ is derated value of } I_D \text{ to cover all worst case operation conditions. } I_{pk} = 1.5 * I_D$$

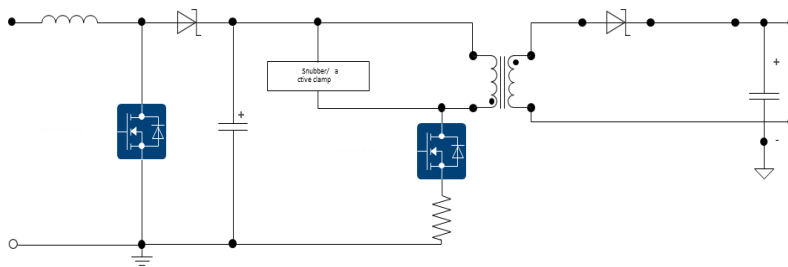
$$P_{device} = (T_J - T_a) / R_{thJA}$$

Output power [W]	Input voltage [V]	PFC output load current at 400 V output voltage [A]	SEMIHOW Device
200	85 V _{AC} ...265 V _{AC}	0.6	HCx60R350T*/HCx60R380*
150	85 V _{AC} ...265 V _{AC}	0.4	HCx60R380
100	85 V _{AC} ...265 V _{AC}	0.3	HCx60R520T
75	85 V _{AC} ...265 V _{AC}	0.2	HCx60R700T

*Two in parallel

• Quasi-resonant flyback topologies

Chargers, Adaptors, Auxiliary power supplies



Design equations for MOSFET selection

$$V_{DS} = V_{in} + VR, \text{ where } VR = (0.8 * V_{out} * (NP / NS))$$

$$I_D = V_{in} * t_{on} / L_p$$

$$V_{DS_FET} = 1.5 * V_{DS} \text{ (with derating for all variables on board)}$$

$$R_{DS(on)} \text{ max. } 25^\circ\text{C for acceptable power dissipation in MOSFET package} \\ = (1.5 * P_{device}) / (I_{pk}^2 * D). I_{pk} \text{ is derated value of } I_D \text{ to cover all worst case operation conditions. } I_{pk} = 1.5 * I_D$$

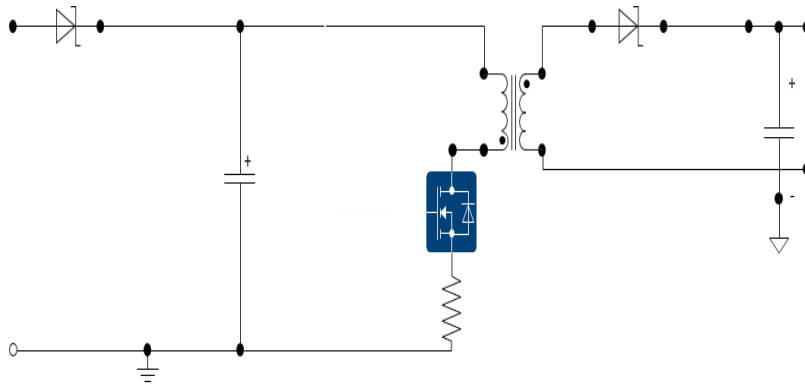
$$P_{device} = (T_J - T_a) / R_{thJA}$$

Output power [W]	Output voltage [V]	inductance DCM [uH]	inductance CCM [uH]	SEMIHOW Device	
				DCM	CCM
120	19	71	143	HCx65R600T	HCx65R600T
100	24	107	214	HCx65R600T	HCx70R950T
75	19	107	214	HCx65R600T	HCx70R950T
50	12	107	214	HCx65R600T	HCx70R950T

APPLICATION

• Wide input range flyback topologies

LED drivers and adaptors



Design equations for MOSFET selection

$$V_{DS} = V_{in} + VR, \text{ where } VR = (0.8 * V_{out} * (NP / NS))$$

$$I_D = V_{in} * t_{on} / L_p$$

$$V_{DS_FET} = 1.5 * V_{DS} \text{ (with derating for all variables on board)}$$

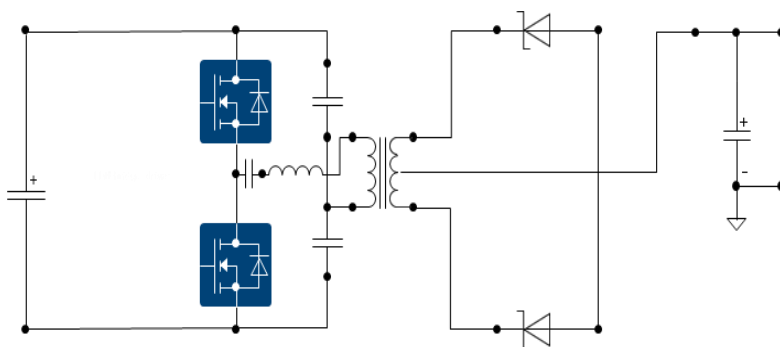
$$R_{DS(on)} \text{ max. } 25^\circ\text{C for acceptable power dissipation in MOSFET package} = (1.5 * P_{device}) / (I_{pk}^2 * D). I_{pk} \text{ is derated value of } I_D \text{ to cover all worst case operation conditions. } I_{pk} = 1.5 * I_D$$

$$P_{device} = (T_j - T_a) / R_{thJA}$$

Output power [W]	Output voltage [V]	Primary inductance DCM [uH]	Primary inductance CCM [uH]	SEMIHOW Device	
				DCM	CCM
150	24	71	143	HCS80R380R	HCS80R500R
100	24	107	214	HCS80R380R	HCS80R650E
50	12	107	214	HCS80R380R	HCS80R650E
36	12	143	286	HCS80R500E	HCS80R650E
25	9	143	286	HCS80R500E	HCS80R650E
15	5	143	286	HCS80R500E	HCS80R650E
10	5	214	429	HCS80R650E	HCS80R1K4E
5	5	429	857	HCS80R1K4E	HCS80R1K4E

• Two switch topologies – half-bridge LLC

PC power and TV power supplies



Design equations for MOSFET selection

$$V_{DS} = V_{in}$$

$$I_D = I_{out} * (NS / NP)$$

$$V_{DS_FET} = 1.5 * V_{DS} \text{ (with derating for all variables on board)}$$

$$R_{DS(on)} \text{ max. } 25^\circ\text{C for acceptable power dissipation in MOSFET package} = (1.5 * P_{device}) / (I_{pk}^2 * D). I_{pk} \text{ is derated value of } I_D \text{ to cover all worst case operation conditions}$$

Input voltage V_{DC} [V]	Output power [W]	Output voltage [V]	SEMIHOW Device
400	250	24	HCx60R350T/HCx60R380
400	200	24	HCx60R350T/HCx60R380
400	150	24	HCx60R520T
400	100	24	HCx60R700T
400	75	24	HCx60R700T

600V SUPER JUNCTION



RDS(on) MAX [mΩ]	TO-220F	TO-220F	TO-252 (DPAK)	TO-251 (IPAK)	TO-247
	WIDE PITCH	NORMAL			
92	HCS60R092EW	HCS60R092E			HCA60R092E
95	HCS60R092TW	HCS60R092T			HCA60R095T
150	HCS60R150TW	HCS60R150T			HCA60R150T
180	HCS60R180EW	HCS60R180E			
350	HCS60R350TW	HCS60R350T	HCD60R350T	HCU60R350T	
380	HCS60R380W	HCS60R380	HCD60R380	HCU60R380	
520	HCS60R520TW	HCS60R520T	HCD60R520T	HCU60R520T	
700	HCS60R700TW	HCS60R700T	HCD60R700T	HCU60R700T	

650V SUPER JUNCTION



RDS(on) MAX [mΩ]	TO-220F	TO-220F	TO-252 (DPAK)	TO-251 (IPAK)	TO-247
	WIDE PITCH	NORMAL			
42					HCA65R042E
69					HCA65R069E
110		HCS65R110E			HCA65R110E
125					HCA65R125E
160	HCS65R160TW	HCS65R160T			HCA65R160T
220		HCS65R220E			
380	HCS65R380TW	HCS65R380T	HCD65R380T	HCU65R380T	
420	HCS65R420W	HCS65R420	HCD65R420	HCU65R420	
600	HCS65R600TW	HCS65R600T	HCD65R600T	HCU65R600T	

700V SUPER JUNCTION



RDS(on) MAX [mΩ]	TO-220F	TO-262 (I2-PAK)	TO-252 (DPAK)	TO-251 (IPAK)	SOT-223
350	HCS70R350E		HCD70R350E		
500	HCS70R500E		HCD70R500E	HCU70R500E	
700	HCS70R700T	HCI70R700T	HCD70R700T	HCU70R700T	
950	HCS70R950T		HCD70R950T	HCU70R950T	
1400	HCS70R1K4P		HCD70R1K4P	HCU70R1K4P	
1500	HCS70R1K5E			HCU70R1K5E	
1600	HCS60R1K6			HCU70R1K6	HCT70R1K6

800V SUPER JUNCTION



RDS(on) MAX [mΩ]	TO-220F	TO-262 (I2-PAK)	TO-252 (DPAK)	TO-251 (IPAK)	SOT-223
250	HCS80R250T				
380	HCS80R380R				
500	HCS80R500R				
650	HCS80R650E		HCD80R650E		
1400	HCS80R1K4E		HCD80R1K4E	HCU80R1K4E	

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